

BAS16LD

Single high-speed switching diode

Rev. 1 — 12 October 2010

Product data sheet

1. Product profile

1.1 General description

Single high-speed switching diode, encapsulated in a SOD882D leadless ultra small Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

1.2 Features and benefits

- High switching speed: $t_{rr} \leq 4$ ns
- Low leakage current
- Repetitive peak reverse voltage: $V_{RRM} \leq 100$ V
- AEC-Q101 qualified
- Low capacitance
- Reverse voltage: $V_R \leq 100$ V
- Ultra small and leadless SMD plastic package
- Solderable side pads

1.3 Applications

- High-speed switching
- General-purpose switching

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_F	forward current		[1] -	-	215	mA
I_R	reverse current	$V_R = 80$ V	-	-	0.5	μ A
V_R	reverse voltage		-	-	100	V
t_{rr}	reverse recovery time		[2] -	-	4	ns

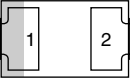
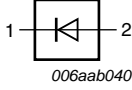
[1] Device mounted on an FR4 Printed-Circuit Board (PCB) with 60 μ m copper strip line.

[2] When switched from $I_F = 10$ mA to $I_R = 10$ mA; $R_L = 100$ Ω ; measured at $I_R = 1$ mA.



2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode	 <p>Transparent top view</p>	
2	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BAS16LD	-	leadless ultra small plastic package; 2 terminals; body 1.0 × 0.6 × 0.4 mm	SOD882D

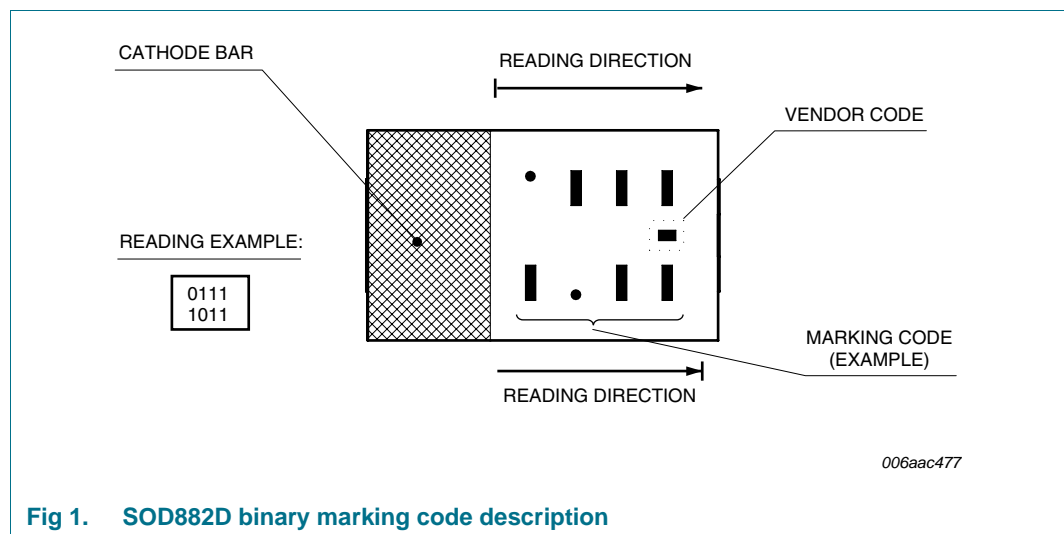
4. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
BAS16LD	1000 0000

[1] For SOD882D binary marking code description, see [Figure 1](#).

4.1 Binary marking code description



5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
V_{RRM}	repetitive peak reverse voltage		-	100	V	
V_R	reverse voltage		-	100	V	
I_F	forward current		[1]	215	mA	
I_{FRM}	repetitive peak forward current	$t_p \leq 0.5 \mu\text{s}$; $\delta \leq 0.25$	-	500	mA	
I_{FSM}	non-repetitive peak forward current	square wave	[2]			
		$t_p = 1 \mu\text{s}$	-	4	A	
		$t_p = 1 \text{ms}$	-	1	A	
		$t_p = 1 \text{s}$	-	0.5	A	
P_{tot}	total power dissipation	$T_{amb} \leq 25 \text{ }^\circ\text{C}$	[1][3]	-	250	mW
T_j	junction temperature		-	150	$^\circ\text{C}$	
T_{amb}	ambient temperature		-55	+150	$^\circ\text{C}$	
T_{stg}	storage temperature		-65	+150	$^\circ\text{C}$	

[1] Device mounted on an FR4 PCB with 60 μm copper strip line.

[2] $T_j = 25 \text{ }^\circ\text{C}$ prior to surge.

[3] Reflow soldering is the only recommended soldering method.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	-	500	K/W

[1] Device mounted on an FR4 PCB with 60 μm copper strip line.

[2] Reflow soldering is the only recommended soldering method.

7. Characteristics

Table 7. Characteristics

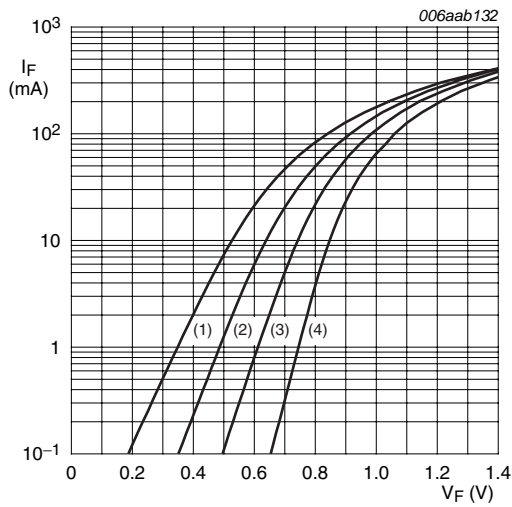
$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage		[1]			
		$I_F = 1\text{ mA}$	-	-	715	mV
		$I_F = 10\text{ mA}$	-	-	855	mV
		$I_F = 50\text{ mA}$	-	-	1	V
		$I_F = 150\text{ mA}$	-	-	1.25	V
I_R	reverse current	$V_R = 25\text{ V}$	-	-	30	nA
		$V_R = 80\text{ V}$	-	-	0.5	μA
		$V_R = 25\text{ V}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	30	μA
		$V_R = 80\text{ V}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	50	μA
C_d	diode capacitance	$f = 1\text{ MHz}; V_R = 0\text{ V}$	-	-	1.5	pF
t_{rr}	reverse recovery time		[2]	-	4	ns
V_{FR}	forward recovery voltage		[3]	-	1.75	V

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.

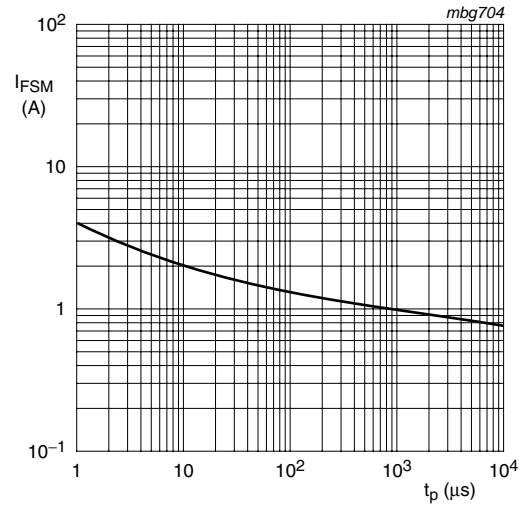
[2] When switched from $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA}$; $R_L = 100\text{ }\Omega$; measured at $I_R = 1\text{ mA}$.

[3] When switched from $I_F = 10\text{ mA}$; $t_r = 20\text{ ns}$.



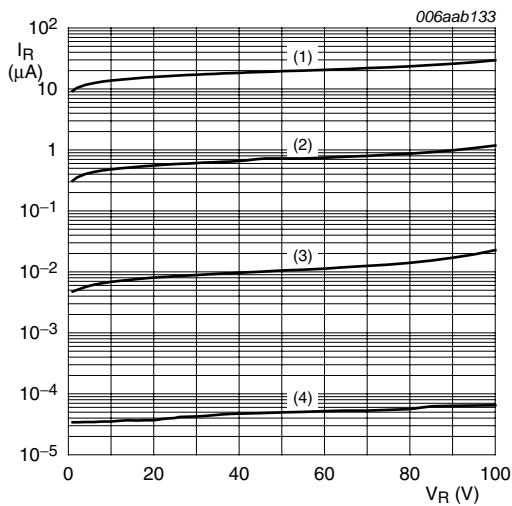
- (1) $T_{amb} = 150\text{ }^\circ\text{C}$
- (2) $T_{amb} = 85\text{ }^\circ\text{C}$
- (3) $T_{amb} = 25\text{ }^\circ\text{C}$
- (4) $T_{amb} = -40\text{ }^\circ\text{C}$

Fig 2. Forward current as a function of forward voltage; typical values



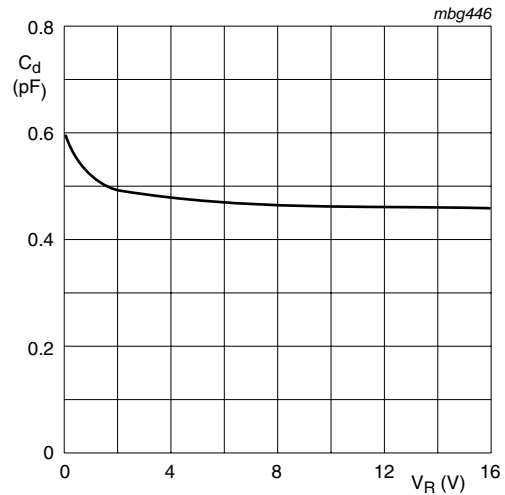
Based on square wave currents.
 $T_j = 25\text{ }^\circ\text{C}$; prior to surge

Fig 3. Non-repetitive peak forward current as a function of pulse duration; maximum values



- (1) $T_{amb} = 150\text{ }^\circ\text{C}$
- (2) $T_{amb} = 85\text{ }^\circ\text{C}$
- (3) $T_{amb} = 25\text{ }^\circ\text{C}$
- (4) $T_{amb} = -40\text{ }^\circ\text{C}$

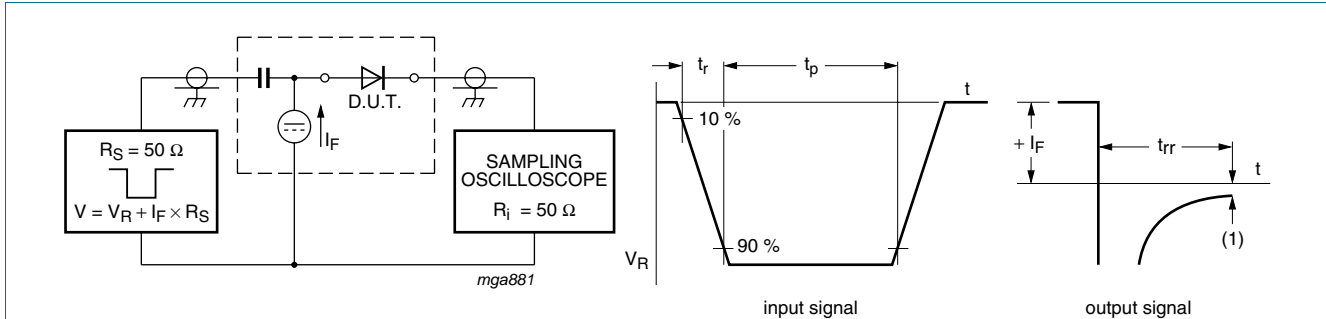
Fig 4. Reverse current as a function of reverse voltage; typical values



$f = 1\text{ MHz}$; $T_{amb} = 25\text{ }^\circ\text{C}$

Fig 5. Diode capacitance as a function of reverse voltage; typical values

8. Test information

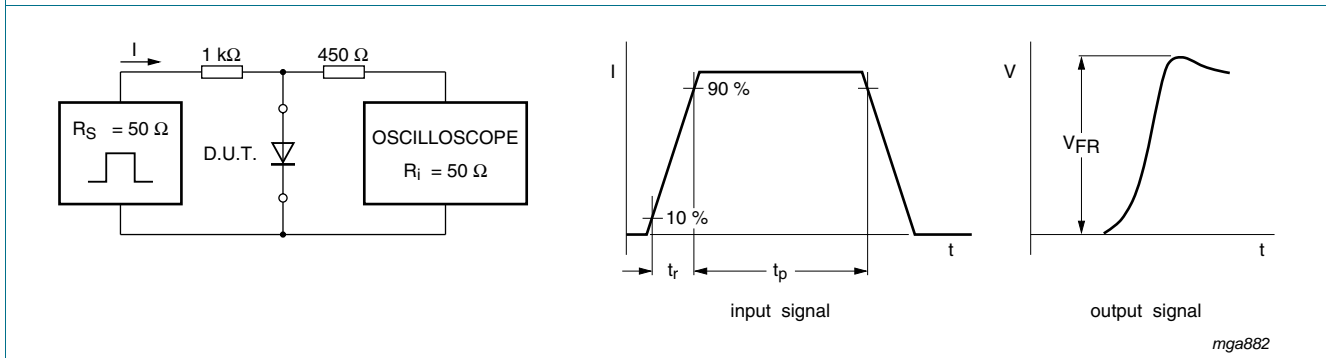


(1) $I_R = 1 \text{ mA}$

Input signal: reverse pulse rise time $t_r = 0.6 \text{ ns}$; reverse voltage pulse duration $t_p = 100 \text{ ns}$; duty cycle $\delta = 0.05$

Oscilloscope: rise time $t_r = 0.35 \text{ ns}$

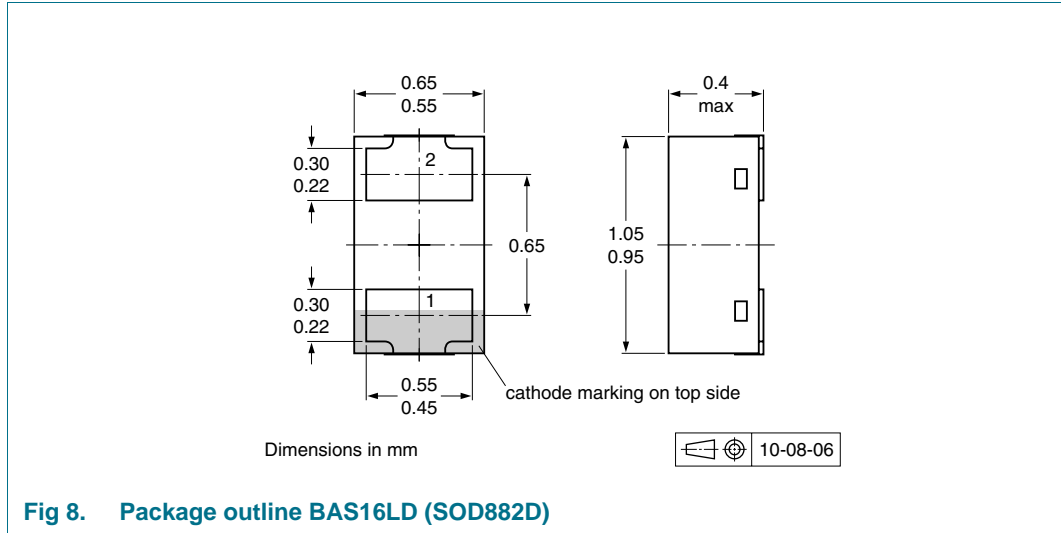
Fig 6. Reverse recovery time test circuit and waveforms



Input signal: forward pulse rise time $t_r = 20 \text{ ns}$; forward current pulse duration $t_p \geq 100 \text{ ns}$; duty cycle $\delta \leq 0.005$

Fig 7. Forward recovery voltage test circuit and waveforms

9. Package outline



10. Packing information

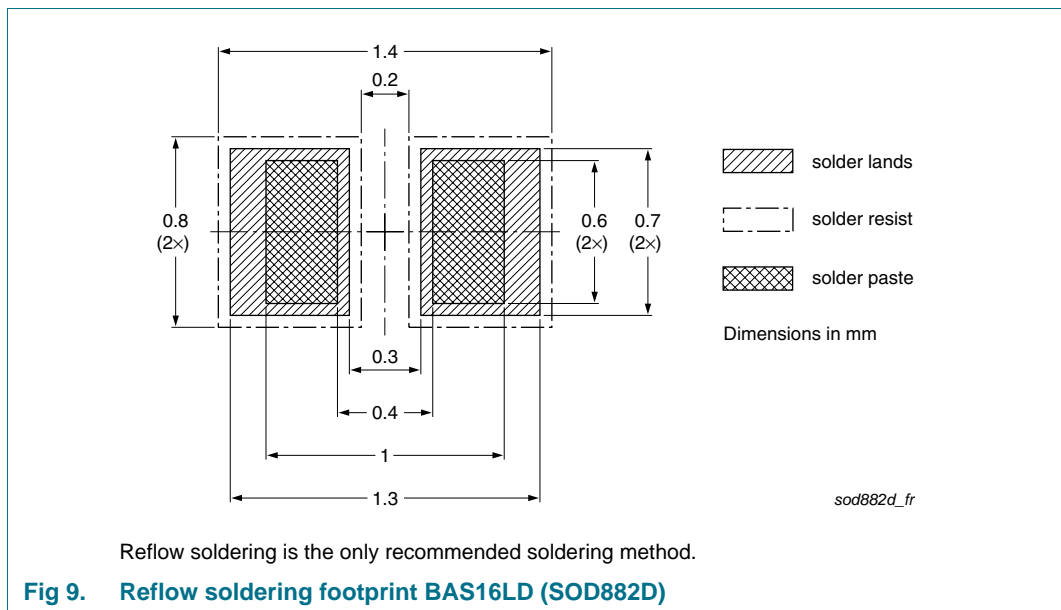
Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity
			10000
BAS16LD	SOD882D	2 mm pitch, 8 mm tape and reel	-315

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering



12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAS16LD v.1	20101012	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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15. Contents

1	Product profile	1
1.1	General description	1
1.2	Features and benefits	1
1.3	Applications	1
1.4	Quick reference data	1
2	Pinning information	2
3	Ordering information	2
4	Marking	2
4.1	Binary marking code description	2
5	Limiting values	3
6	Thermal characteristics	3
7	Characteristics	4
8	Test information	6
9	Package outline	7
10	Packing information	7
11	Soldering	7
12	Revision history	8
13	Legal information	9
13.1	Data sheet status	9
13.2	Definitions	9
13.3	Disclaimers	9
13.4	Trademarks	10
14	Contact information	10
15	Contents	11

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